

GLOSSARY OF TECHNICAL TERMS

This glossary of technical terms contains explanations of certain technical terms used in this document in connection with our Company and our business. Such terminology and meanings may not correspond to standard industry meanings or usages of those terms.

“AEC-Q100”	a failure mechanism based stress test qualification for packaged integrated circuit
“ASIC”	application-specific IC, a type of motor control chip that is customized to the needs of a specific application
“BI system”	business intelligence system, a decision support information management tool, facilitating users to aggregate, catalogue and analyze business data from numerous sources within or outside the organization
“CoWoS”	Chip-on-Wafer-on-Substrate, an advanced packaging technology that offers the advantage of a larger package size and more I/O connection
“CPU”	central processing unit, a complex set of electronic circuitry that runs the machine’s operating system and applications
“DDR”	double data rate, an industry standard for SDRAM products introduced by JEDEC
“DIMM”	dual inline memory module, a type of memory module that features a series of DRAM integrated circuits mounted on a printed circuit board, with electrical contacts on both sides to connect to a device’s motherboard, providing volatile storage for data processing. Major types of DIMMs include Registered DIMM (“ RDIMM ”), Small Outline DIMM (“ SODIMM ”), and Unbuffered DIMM (“ UDIMM ”), each designed to cater to specific performance and form factor requirements in various computing environment
“DRAM”	dynamic random-access memory, a type of random-access memory that requires periodic refreshing to maintain the stored information. Because of this refresh requirement, it is a “dynamic”, or volatile, memory, as opposed to a non-volatile, or “static”, memory that keeps its contents when the power is turned off
“ECC”	error correction code, a method used to detect and correct errors in data transmission or storage
“GB”	gigabyte, a measure of computer data storage capacity that is roughly equivalent to 1 billion bytes
“Gb”	gigabit, a unit of digital information equal to one billion bits
“GDDR”	Graphic DDR, a high-performance DDR memory specification specifically designed for graphics cards

GLOSSARY OF TECHNICAL TERMS

“GPU”	graphic processing unit, a specialized electronic circuit designed to rapidly manipulate and alter memory to accelerate the creation of images
“HBM”	high-bandwidth memory, a type of memory used in high-performance computing and graphics applications, offering high-speed data transfer rates and increased bandwidth through advanced packaging techniques
“HSM”	hybrid-stacked memory, a type of memory currently under development by our Company which is aimed to be comparable to or better than JEDEC HBM standards in terms of performance
“IC” or “Integrated circuit”	integrated circuit, a type of miniature electronic device or component, manufactured using semiconductor techniques, integrating all the necessary transistors, resistors, capacitors, inductors and their connecting wires for a circuit onto a small semiconductor wafer (such as a silicon chip or substrate), which is then soldered and encapsulated within a casing to form an electronic device with the desired circuit functions
“IDM”	integrated device manufacturer, a company that designs, manufactures and sells its own products, handling the entire production process from design to fabrication and distribution, and in the context of the semiconductor industry, a company that covers the entire business segment, including chip design, wafer manufacturing and packaging and testing
“IEEE”	Institute of Electrical and Electronics Engineers, the world’s largest association of technical professionals established for the advancement of technology
“IoT”	internet of things, a network of interconnected devices that communicate and exchange data with each other over the internet
“JEDEC”	Joint Electron Device Engineering Council, a standardization institution in the solid-state and semiconductor industry that develops industry standards for solid-state electronics
“KGD”	Known Good Die, a bare die or unpackaged chip that has undergone extensive testing and is confirmed to possess the same quality, reliability, and functionality as the packaged product, meeting specified functional and specification standards
“LLM”	large language model, an AI model trained on extensive text data to understand and generate human language, capable of tasks such as translation, summarization, and question answering

GLOSSARY OF TECHNICAL TERMS

“LPDDR”	low power double data rate, an industry standard for low-power SDRAM products introduced by the JEDEC
“Mb”	megabit, a unit of digital information equal to approximately one million bits
“MBIST”	Memory Built-In Self-Test, a self-testing and repair mechanism which tests the memories through an effective set of algorithms to detect possibly all the faults that could be present inside a typical memory cell
“MHz”	megahertz, a unit of alternating current or electromagnetic wave frequency equal to one million hertz
“OSAT Company(ies)”	outsourced semiconductor assembly and test companies that provide third-party IC packaging and testing services
“PCB”	printed circuit board, a board used in electronics to connect electronic components using conductive pathways, tracks, or signal traces etched from copper sheets laminated onto a non-conductive substrate
“RDL”	redistribution layer, an extra metal layer on an integrated circuit that makes its I/O pads available in other locations of the chip, for better access to the pads where necessary
“SDR”	single data rate, an industry standard for SDRAM products introduced by JEDEC where data is transferred once per clock cycle
“SDRAM”	synchronous dynamic random-access memory, a type of DRAM that uses synchronous interface
“SiP”	system-in-package, a type of chip packaging technology that combines multiple electronic components, such as processors, memory and sensors, passive components, and other electronic components into a single package, offering high integration, design flexibility and reduced space for compact electronic devices
“SoC”	system-on-chips, an integrated circuit that integrates most or all components of a computer or other electronic system
“SRAM”	static random access memory, a type of random access memory that uses bi-stable latching circuitry to store each bit, providing faster access times than DRAM and not requiring periodic refreshing
“TSV”	Through Silicon Via, a packaging technology that replaces the conventional wires used to connect chips